

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of -40°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree[†]**
- **1 A Low-Dropout Voltage Regulator**
- **Available in 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, 5.0-V Fixed Output and Adjustable Versions**
- **Dropout Voltage Down to 230 mV at 1 A (TPS76750)**
- **Ultralow 85 μA Typical Quiescent Current**

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **Fast Transient Response**
- **2% Tolerance Over Specified Conditions for Fixed-Output Versions**
- **Open Drain Power-On Reset With 200-ms Delay (See TPS768xx for PG Option)**
- **20-Pin TSSOP PowerPAD™ (PWP) Package**
- **Thermal Shutdown Protection**

**PWP PACKAGE
(TOP VIEW)**

GND/HSINK	1	20	GND/HSINK
GND/HSINK	2	19	GND/HSINK
GND	3	18	NC
NC	4	17	NC
EN	5	16	RESET
IN	6	15	FB/NC
IN	7	14	OUT
NC	8	13	OUT
GND/HSINK	9	12	GND/HSINK
GND/HSINK	10	11	GND/HSINK

NC – No internal connection

description

This device is designed to have a fast transient response and be stable with 10- μF low ESR capacitors. This combination provides high performance at a reasonable cost.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 230 mV at an output current of 1 A for the TPS76750) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85 μA over the full range of output current, 0 mA to 1 A). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to EN (enable) shuts down the regulator, reducing the quiescent current to 1 μA at $T_J = 25^{\circ}\text{C}$.

The RESET output of the TPS767xx initiates a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS767xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage.

The TPS767xx is offered in 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, and 5.0-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS767xx family is available in a 20-pin PWP package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

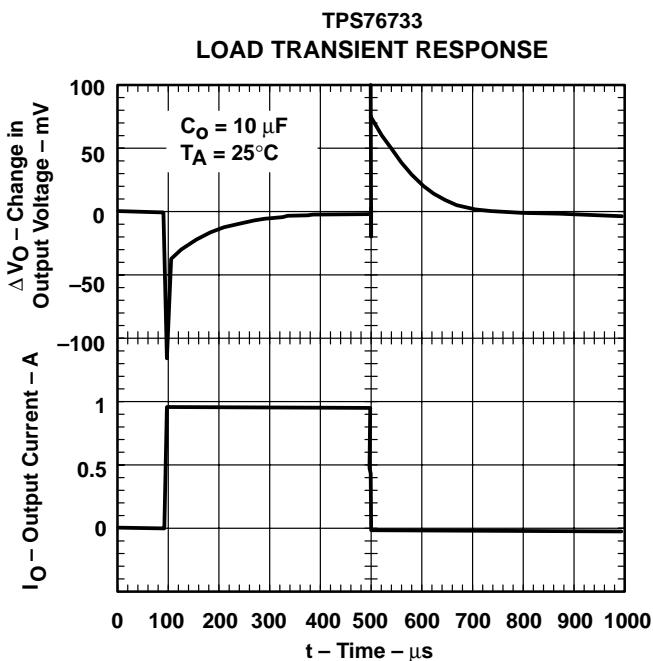
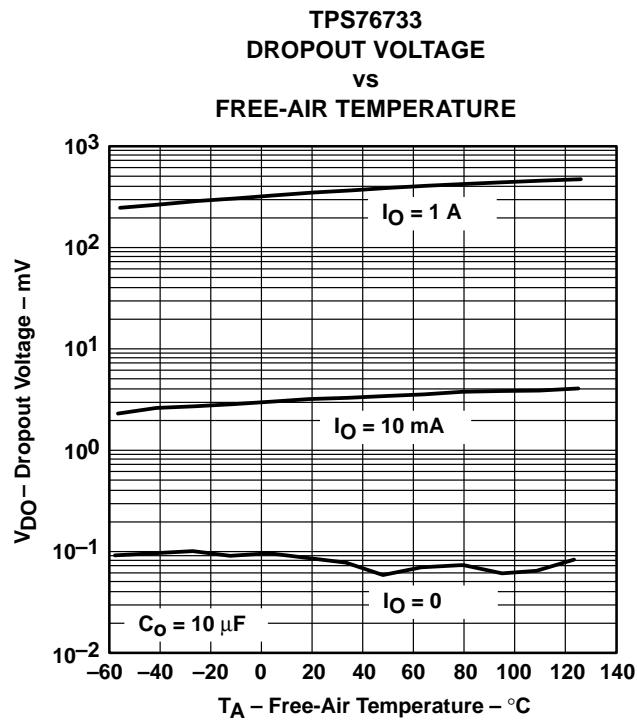
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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**TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76727-EP
 TPS76728-EP, TPS76730-EP, TPS76733-EP, TPS76750-EP, TPS76701-EP
 FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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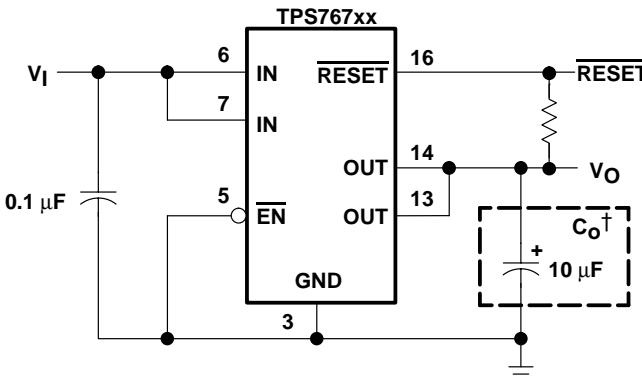


AVAILABLE OPTIONS

T_J	OUTPUT VOLTAGE (V)	TSSOP (PWP) [†]
	TYP	
-40°C to 125°C	5.0	TPS76750QPWPREP
	3.3	TPS76733QPWPREP
	3.0	TPS76730QPWPREP [‡]
	2.8	TPS76728QPWPREP [‡]
	2.7	TPS76727QPWPREP [‡]
	2.5	TPS76725QPWPREP
	1.8	TPS76718QPWPREP
	1.5	TPS76715QPWPREP
	Adjustable 1.5 V to 5.5 V	TPS76701QPWPREP

[†] Available taped and reeled in quantities of 2000 per reel.

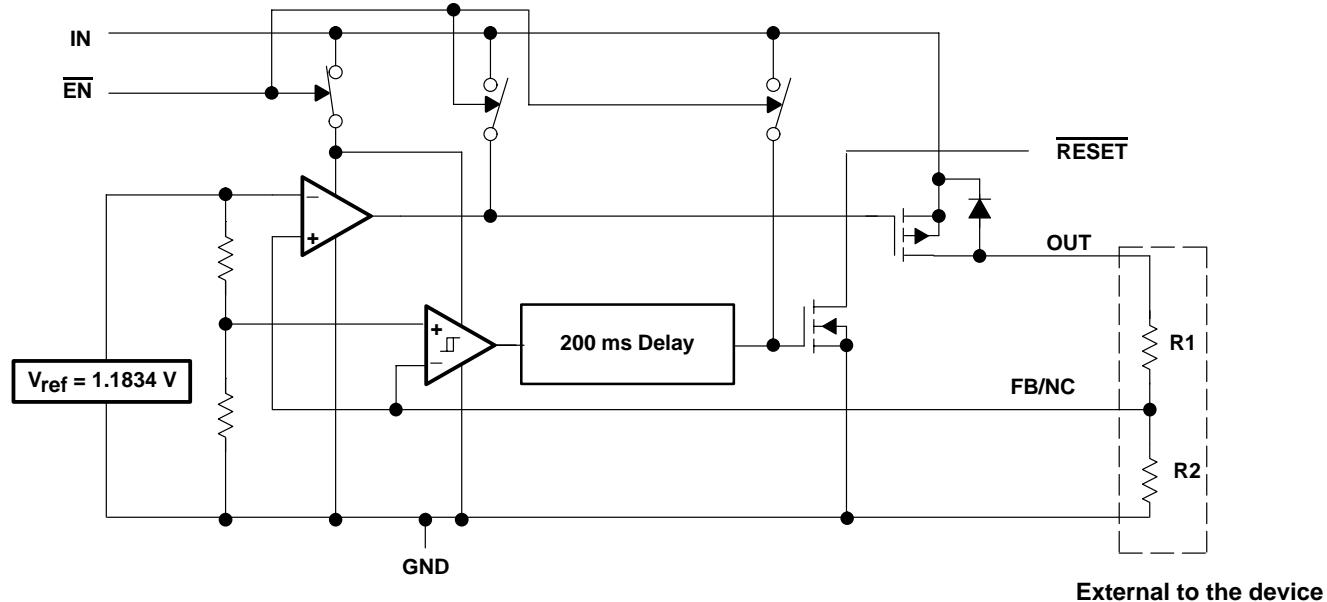
[‡] This device is product preview.



† See application information section for capacitor selection details.

Figure 1. Typical Application Configuration (For Fixed Output Options)

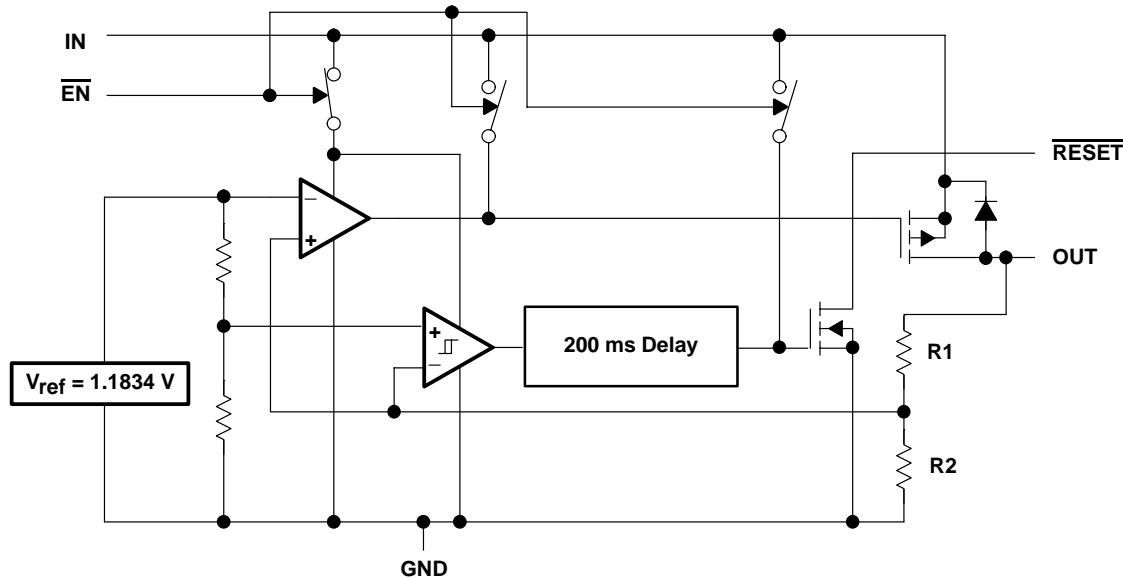
functional block diagram—adjustable version



**TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76727-EP
 TPS76728-EP, TPS76730-EP, TPS76733-EP, TPS76750-EP, TPS76701-EP
 FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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functional block diagram—fixed-voltage version

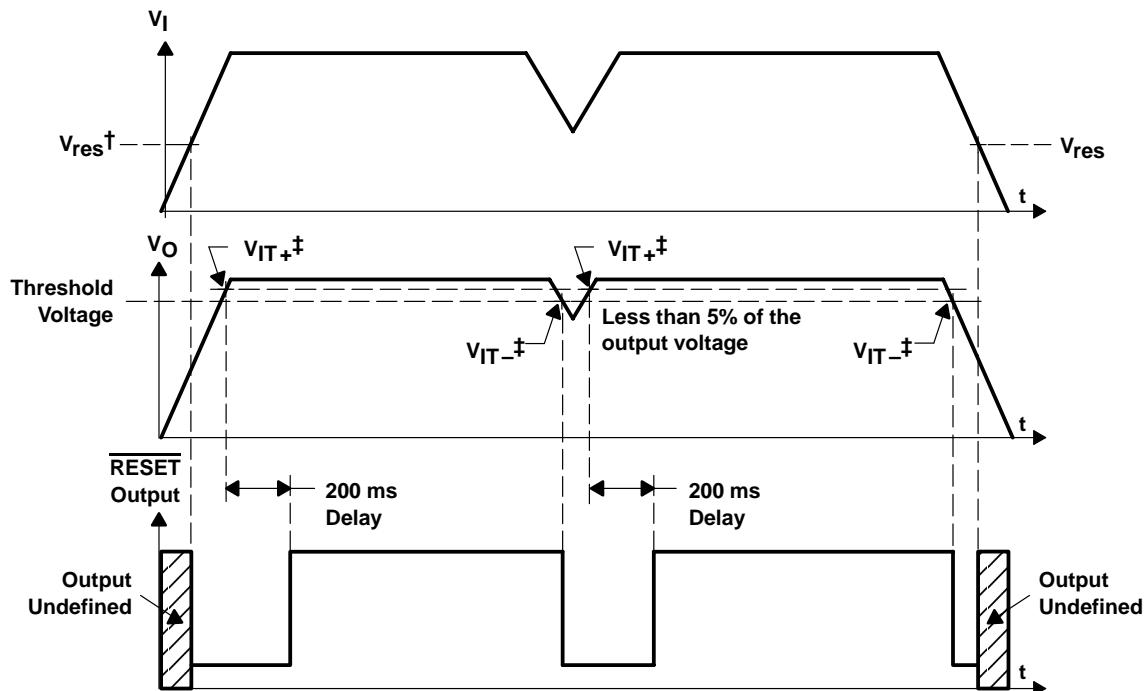


Terminal Functions

PWP Package

TERMINAL NAME	NO.	I/O	DESCRIPTION
\overline{EN}	5	I	Enable input
FB/NC	15	I	Feedback input voltage for adjustable device (no connect for fixed options)
GND	3		Regulator ground
GND/HSINK	1, 2, 9, 10, 11, 12, 19, 20		Ground/heatsink
IN	6, 7	I	Input voltage
NC	4, 8, 17, 18		No connect
OUT	13, 14	O	Regulated output voltage
RESET	16	O	\overline{RESET} output

timing diagram



† V_{res} is the minimum input voltage for a valid RESET. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology.

‡ V_{IT-} –Trip voltage is typically 5% lower than the output voltage (95% V_O) V_{IT-} to V_{IT+} is the hysteresis voltage.

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 FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage range [‡] , V_I	–0.3 V to 13.5 V
Voltage range at $\bar{E}N$	–0.3 V to $V_I + 0.3$ V
Maximum $\bar{R}ESET$ voltage	16.5 V
Peak output current	Internally limited
Output voltage, V_O (OUT, FB)	7 V
Continuous total power dissipation	See dissipation rating tables
Operating virtual junction temperature range, T_J	–40°C to 125°C
Storage temperature range, T_{stg}	–65°C to 150°C
ESD rating, HBM	2 kV

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[‡] All voltage values are with respect to network terminal ground.

DISSIPATION RATING TABLE – FREE-AIR TEMPERATURES

PACKAGE	AIR FLOW (CFM)	$T_A < 25^\circ C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ C$	$T_A = 70^\circ C$ POWER RATING	$T_A = 85^\circ C$ POWER RATING
PWP [§]	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
PWP [¶]	0	3 W	23.8 mW/°C	1.9 W	1.5 W
	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

[§] This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in \times 5-in PCB, 1 oz. copper, 2-in \times 2-in coverage (4 in²).

[¶] This parameter is measured with the recommended copper heat sink pattern on a 8-layer PCB, 1.5-in \times 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in²) and layers 3 and 6 at 100% coverage (6 in²). For more information, refer to TI technical brief SLMA002.

recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V_I [#]	2.7	10	V
Output voltage range, V_O	1.5	5.5	V
Output current, I_O (see Note 1)	0	1.0	A
Operating virtual junction temperature, T_J (see Note 1)	–40	125	°C

[#] To calculate the minimum input voltage for your maximum output current, use the following equation: $V_I(\min) = V_O(\max) + V_{DO}(\max \text{ load})$.
 NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

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FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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**electrical characteristics over recommended operating free-air temperature range,
 $V_I = V_O(\text{typ}) + 1 \text{ V}$, $I_O = 1 \text{ mA}$, $\bar{E}N = 0 \text{ V}$, $C_O = 10 \mu\text{F}$ (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output voltage (10 μA to 1 A load) (see Note 2)	TPS76701 $1.5 \text{ V} \leq V_O \leq 5.5 \text{ V}$, $T_J = 25^\circ\text{C}$		V_O		
	$1.5 \text{ V} \leq V_O \leq 5.5 \text{ V}$, $T_J = -40^\circ\text{C}$ to 125°C	0.98 V_O		1.02 V_O	
	TPS76715 $T_J = 25^\circ\text{C}$, $2.7 \text{ V} < V_{IN} < 10 \text{ V}$		1.5		
		$T_J = -40^\circ\text{C}$ to 125°C , $2.7 \text{ V} < V_{IN} < 10 \text{ V}$	1.470	1.530	
	TPS76718 $T_J = 25^\circ\text{C}$, $2.8 \text{ V} < V_{IN} < 10 \text{ V}$		1.8		
		$T_J = -40^\circ\text{C}$ to 125°C , $2.8 \text{ V} < V_{IN} < 10 \text{ V}$	1.764	1.836	
	TPS76725 $T_J = 25^\circ\text{C}$, $3.5 \text{ V} < V_{IN} < 10 \text{ V}$		2.5		
		$T_J = -40^\circ\text{C}$ to 125°C , $3.5 \text{ V} < V_{IN} < 10 \text{ V}$	2.450	2.550	
	TPS76727 $T_J = 25^\circ\text{C}$, $3.7 \text{ V} < V_{IN} < 10 \text{ V}$		2.7		
		$T_J = -40^\circ\text{C}$ to 125°C , $3.7 \text{ V} < V_{IN} < 10 \text{ V}$	2.646	2.754	
	TPS76728 $T_J = 25^\circ\text{C}$, $3.8 \text{ V} < V_{IN} < 10 \text{ V}$		2.8		
		$T_J = -40^\circ\text{C}$ to 125°C , $3.8 \text{ V} < V_{IN} < 10 \text{ V}$	2.744	2.856	
	TPS76730 $T_J = 25^\circ\text{C}$, $4.0 \text{ V} < V_{IN} < 10 \text{ V}$		3.0		
		$T_J = -40^\circ\text{C}$ to 125°C , $4.0 \text{ V} < V_{IN} < 10 \text{ V}$	2.940	3.060	
	TPS76733 $T_J = 25^\circ\text{C}$, $4.3 \text{ V} < V_{IN} < 10 \text{ V}$		3.3		
		$T_J = -40^\circ\text{C}$ to 125°C , $4.3 \text{ V} < V_{IN} < 10 \text{ V}$	3.234	3.366	
	TPS76750 $T_J = 25^\circ\text{C}$, $6.0 \text{ V} < V_{IN} < 10 \text{ V}$		5.0		
		$T_J = -40^\circ\text{C}$ to 125°C , $6.0 \text{ V} < V_{IN} < 10 \text{ V}$	4.900	5.100	
Quiescent current (GND current) $\bar{E}N = 0 \text{ V}$, (see Note 2)	$10 \mu\text{A} < I_O < 1 \text{ A}$, $T_J = 25^\circ\text{C}$		85		
	$I_O = 1 \text{ A}$, $T_J = -40^\circ\text{C}$ to 125°C			125	μA
Output voltage line regulation ($\Delta V_O/V_O$) (see Notes 2 and 3)	$V_O + 1 \text{ V} < V_I \leq 10 \text{ V}$, $T_J = 25^\circ\text{C}$	0.01			%/V
Load regulation			3		mV
Output noise voltage (TPS76718)	$BW = 200 \text{ Hz}$ to 100 kHz , $I_C = 1 \text{ A}$, $C_O = 10 \mu\text{F}$, $T_J = 25^\circ\text{C}$	55			μVrms
Output current limit	$V_O = 0 \text{ V}$	1.7	2		A
Thermal shutdown junction temperature		150			$^\circ\text{C}$
Standby current	$\bar{E}N = V_I$, $T_J = 25^\circ\text{C}$, $2.7 \text{ V} < V_I < 10 \text{ V}$	1			μA
	$\bar{E}N = V_I$, $T_J = -40^\circ\text{C}$ to 125°C $2.7 \text{ V} < V_I < 10 \text{ V}$		10		μA
FB input current	TPS76701	FB = 1.5 V	2		nA
High level enable input voltage			1.7		V
Low level enable input voltage			0.9		V
Power supply ripple rejection (see Note 2)	$f = 1 \text{ KHz}$, $T_J = 25^\circ\text{C}$	$C_O = 10 \mu\text{F}$	60		dB

NOTES: 2. Minimum IN operating voltage is 2.7 V or $V_O(\text{typ}) + 1 \text{ V}$, whichever is greater. Maximum IN voltage 10V.

3. If $V_O \leq 1.8 \text{ V}$ then $V_{I\text{max}} = 10 \text{ V}$, $V_{I\text{min}} = 2.7 \text{ V}$:

$$\text{Line Reg. (mV)} = (\%/\text{V}) \times \frac{V_O(V_{I\text{max}} - 2.7 \text{ V})}{100} \times 1000$$

If $V_O \geq 2.5 \text{ V}$ then $V_{I\text{max}} = 10 \text{ V}$, $V_{I\text{min}} = V_O + 1 \text{ V}$:

$$\text{Line Reg. (mV)} = (\%/\text{V}) \times \frac{V_O(V_{I\text{max}} - (V_O + 1 \text{ V}))}{100} \times 1000$$



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 FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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**electrical characteristics over recommended operating free-air temperature range,
 $V_I = V_O(\text{typ}) + 1 \text{ V}$, $I_O = 1 \text{ mA}$, $\bar{E}N = 0 \text{ V}$, $C_O = 10 \mu\text{F}$ (unless otherwise noted) (continued)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Reset	Minimum input voltage for valid RESET	$I_O(\text{RESET}) = 300 \mu\text{A}$	1.1			V
	Trip threshold voltage	V_O decreasing	92	98		% V_O
	Hysteresis voltage	Measured at V_O		0.5		% V_O
	Output low voltage	$V_I = 2.7 \text{ V}$, $I_O(\text{RESET}) = 1 \text{ mA}$	0.15	0.4		V
	Leakage current	$V(\text{RESET}) = 5 \text{ V}$		1		μA
	RESET time-out delay		200			ms
Input current ($\bar{E}N$)	$\bar{E}N = 0 \text{ V}$		-1	0	1	μA
	$\bar{E}N = V_I$		-1	1		
Dropout voltage (see Note 4)	TPS76728	$I_O = 1 \text{ A}$, $T_J = 25^\circ\text{C}$	500			mV
		$I_O = 1 \text{ A}$, $T_J = -40^\circ\text{C}$ to 125°C	825			
	TPS76730	$I_O = 1 \text{ A}$, $T_J = 25^\circ\text{C}$	450			
		$I_O = 1 \text{ A}$, $T_J = -40^\circ\text{C}$ to 125°C	675			
	TPS76733	$I_O = 1 \text{ A}$, $T_J = 25^\circ\text{C}$	350			
		$I_O = 1 \text{ A}$, $T_J = -40^\circ\text{C}$ to 125°C	575			
	TPS76750	$I_O = 1 \text{ A}$, $T_J = 25^\circ\text{C}$	230			
		$I_O = 1 \text{ A}$, $T_J = -40^\circ\text{C}$ to 125°C	380			

NOTE 4: IN voltage equals $V_O(\text{typ}) - 100 \text{ mV}$; TPS76701 output voltage set to 3.3 V nominal with external resistor divider. TPS76715, TPS76718, TPS76725, and TPS76727 dropout voltage limited by input voltage range limitations (i.e., TPS76730 input voltage needs to drop to 2.9 V for purpose of this test).

TYPICAL CHARACTERISTICS

Table of Graphs

		FIGURE
V_O	Output voltage	vs Output current
		vs Free-air temperature
Ground current		vs Free-air temperature
Power supply ripple rejection		vs Frequency
Output spectral noise density		vs Frequency
Input voltage (min)		vs Output voltage
Z_O	Output impedance	vs Frequency
V_{DO}	Dropout voltage	vs Free-air temperature
	Line transient response	
	Load transient response	
V_O	Output voltage	vs Time
	Dropout voltage	vs Input voltage
	Equivalent series resistance (ESR)	vs Output current

TYPICAL CHARACTERISTICS

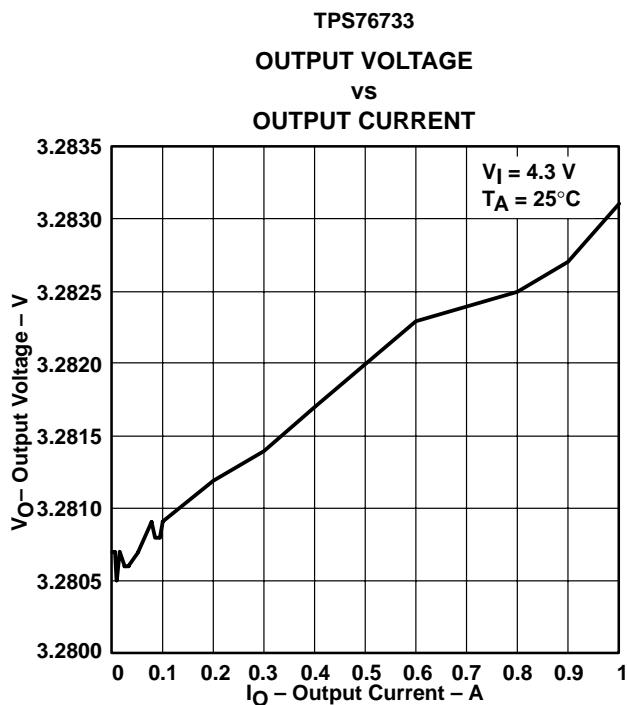


Figure 2

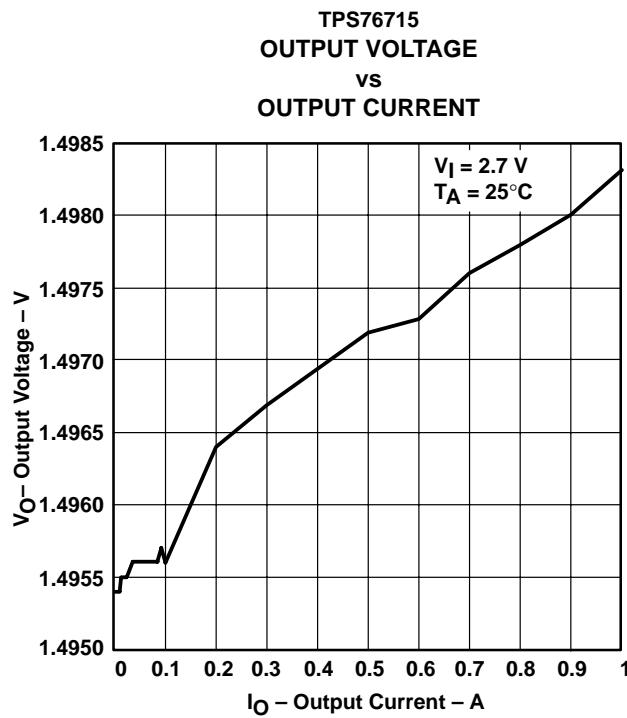


Figure 3

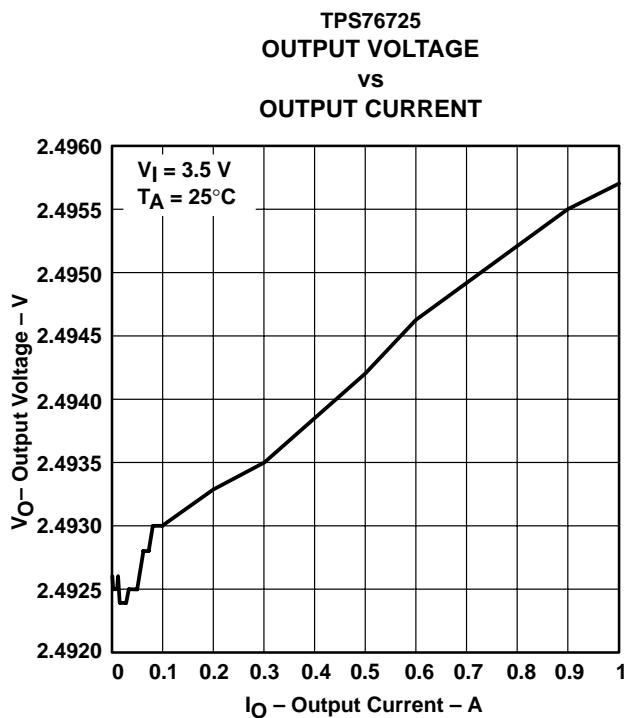


Figure 4

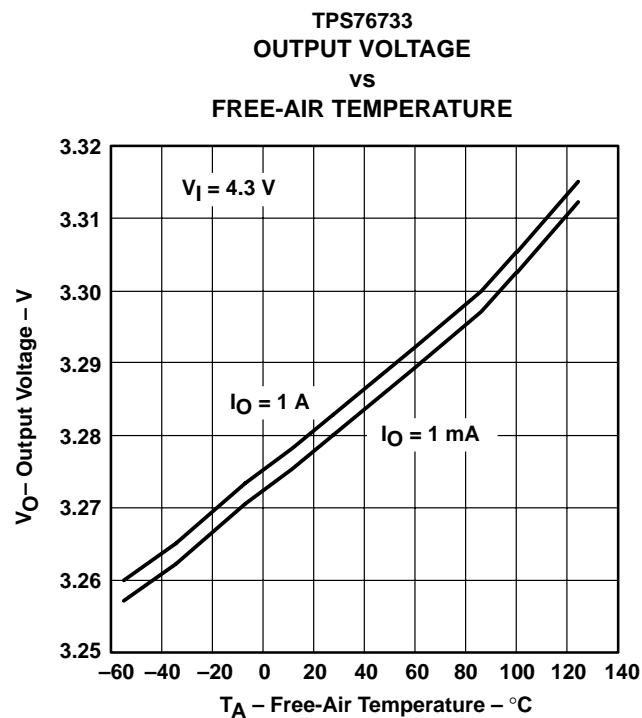


Figure 5

**TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76727-EP
 TPS76728-EP, TPS76730-EP, TPS76733-EP, TPS76750-EP, TPS76701-EP
 FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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TYPICAL CHARACTERISTICS

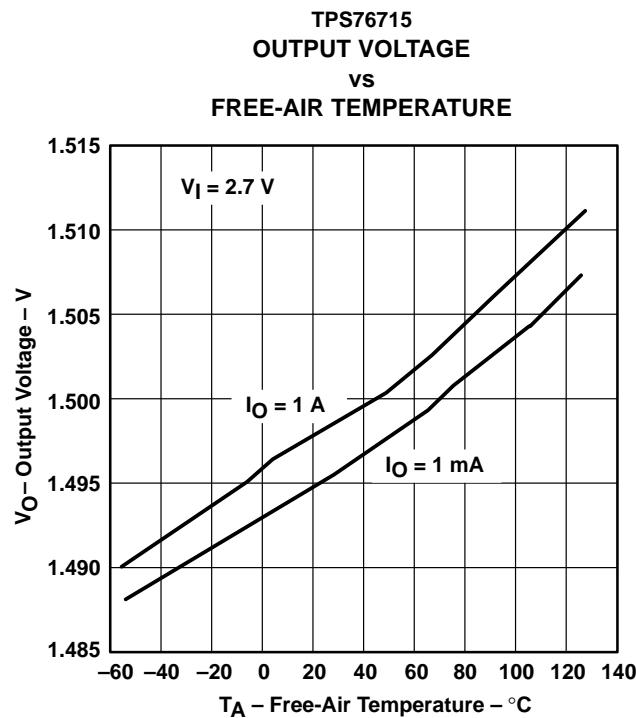


Figure 6

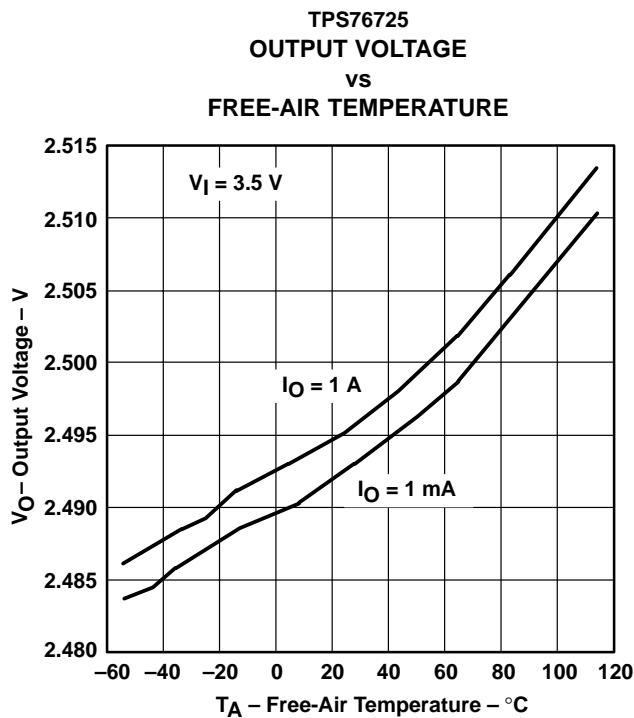


Figure 7

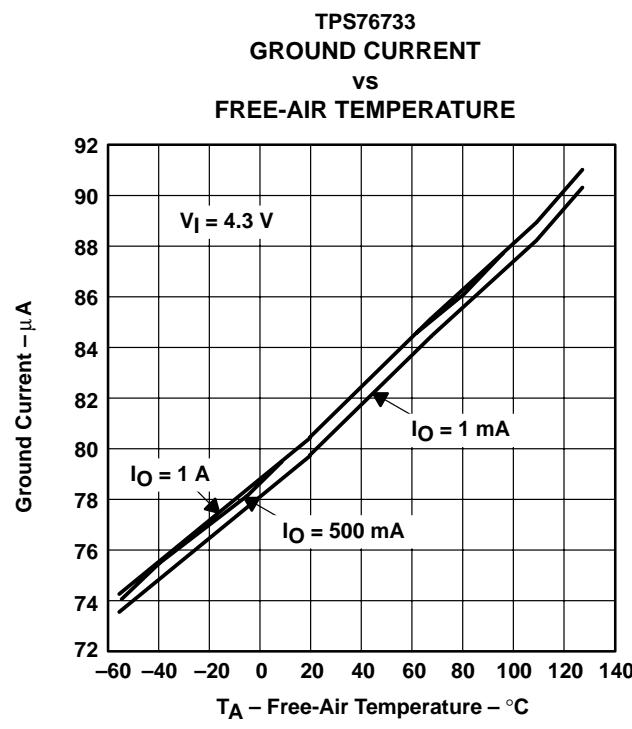
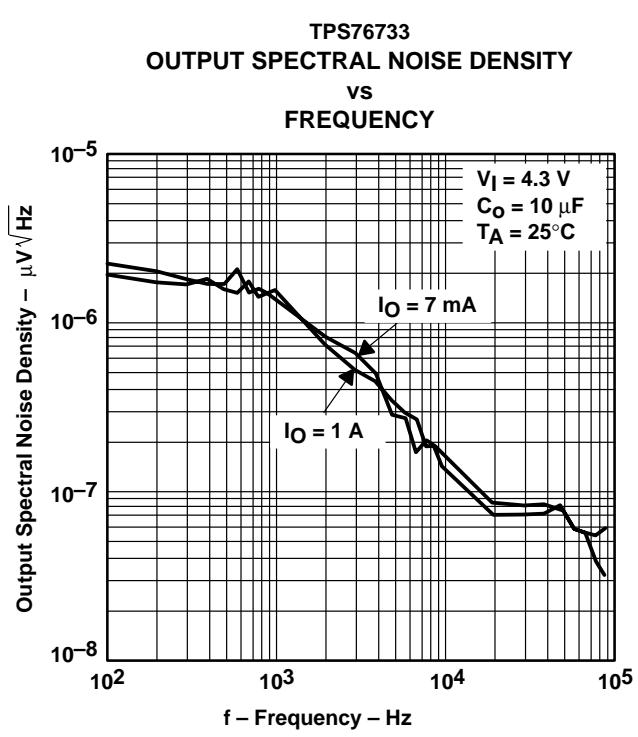
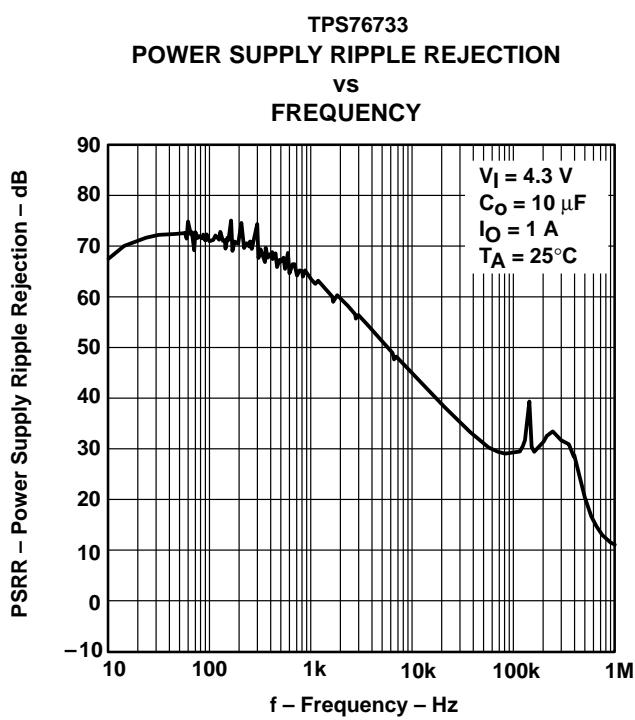
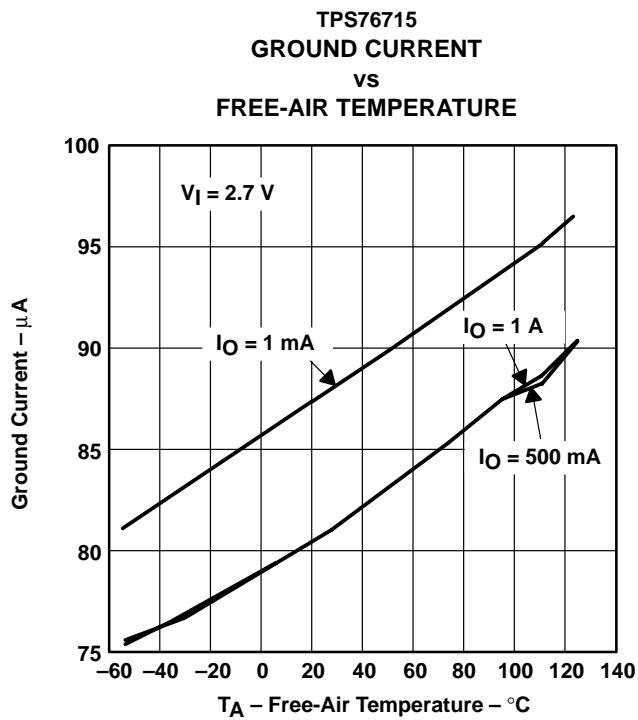


Figure 8

TYPICAL CHARACTERISTICS



**TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76727-EP
 TPS76728-EP, TPS76730-EP, TPS76733-EP, TPS76750-EP, TPS76701-EP
 FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

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TYPICAL CHARACTERISTICS

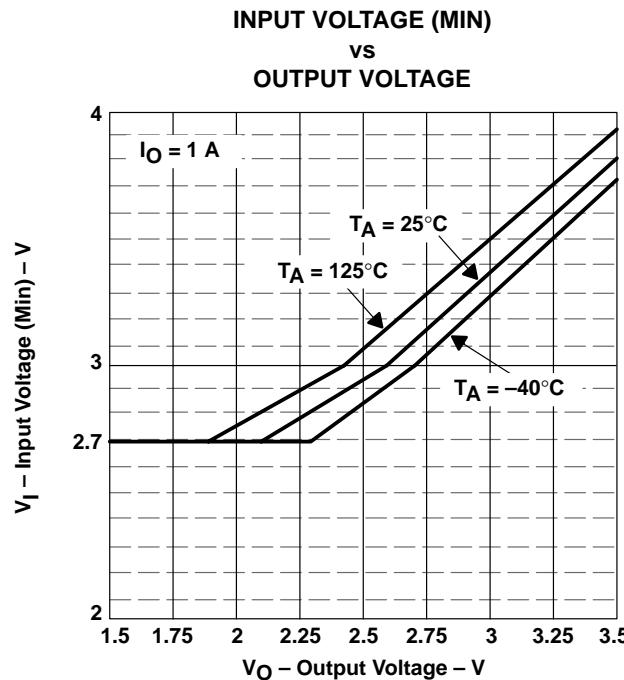


Figure 12

**TPS76733
 OUTPUT IMPEDANCE
 vs
 FREQUENCY**

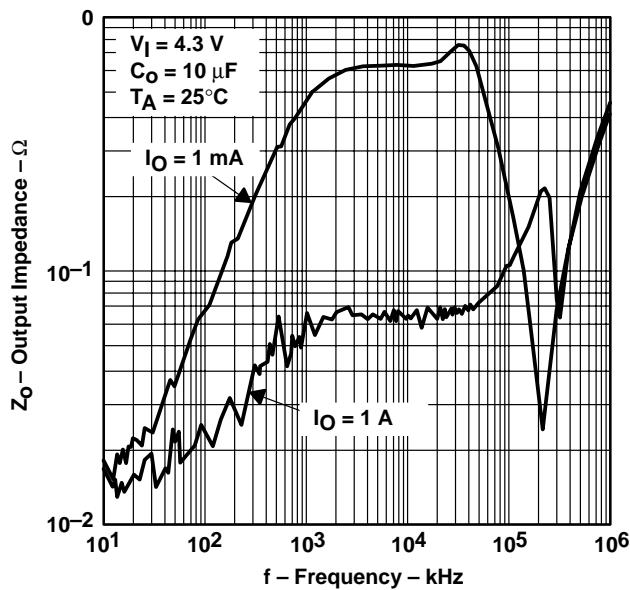


Figure 13

**TPS76733
 DROPOUT VOLTAGE
 vs
 FREE-AIR TEMPERATURE**

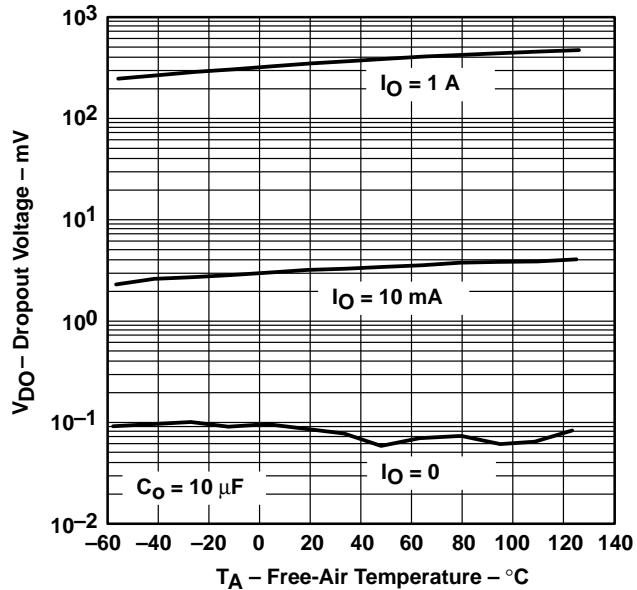


Figure 14

TYPICAL CHARACTERISTICS

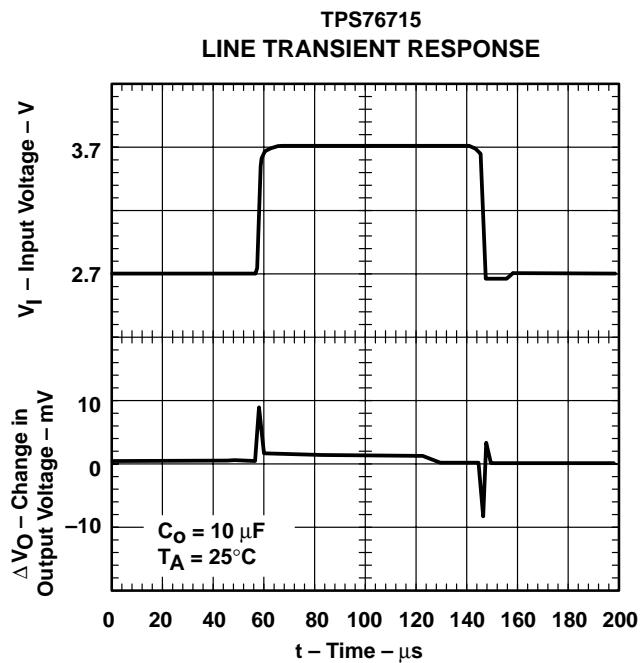


Figure 15

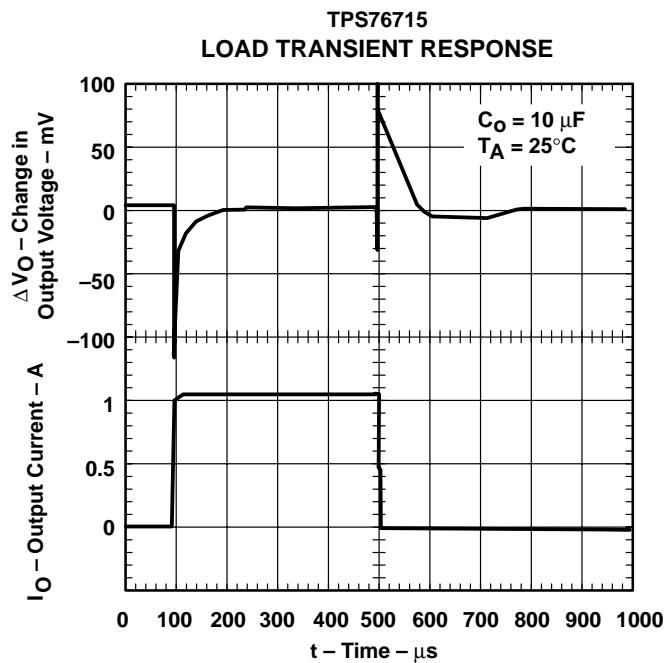


Figure 16

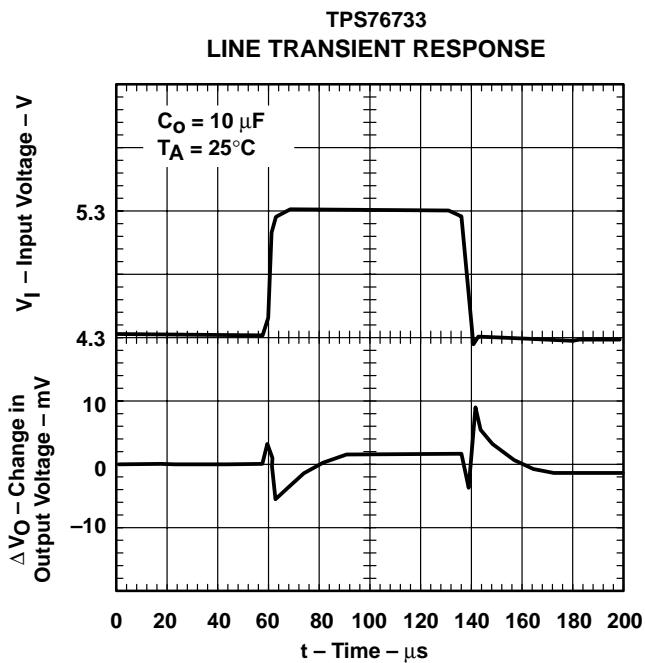


Figure 17

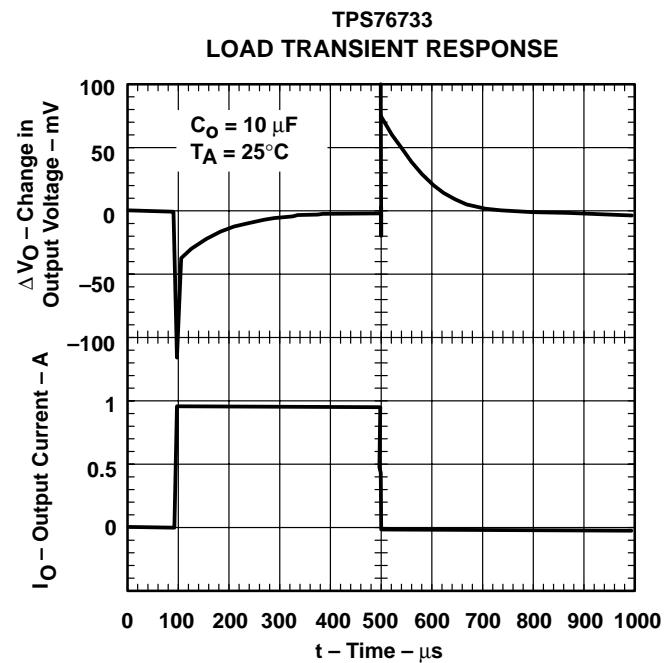


Figure 18

**TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76727-EP
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TYPICAL CHARACTERISTICS

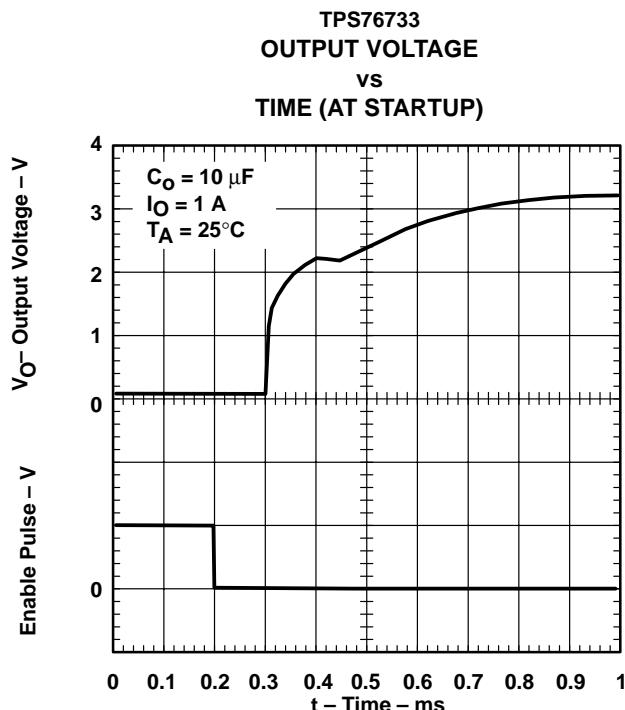


Figure 19

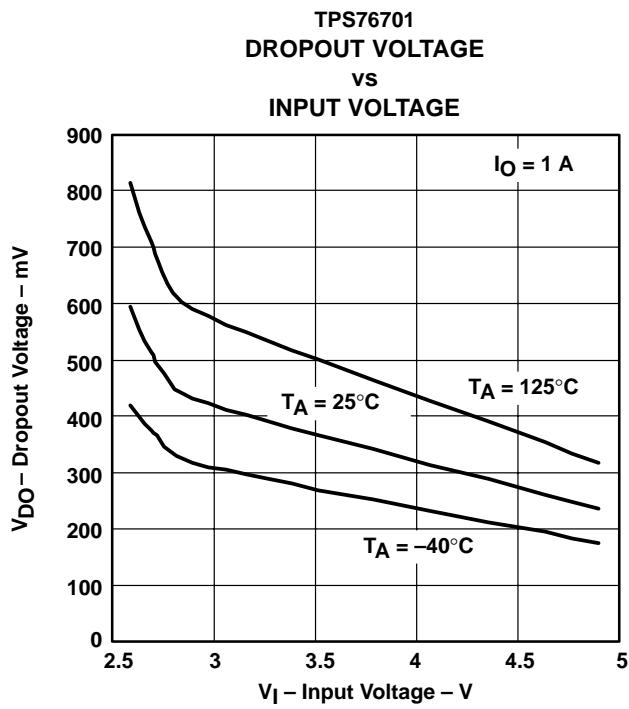


Figure 20

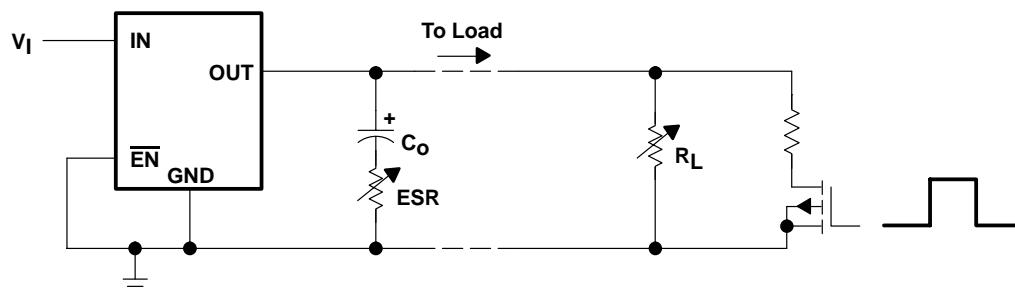


Figure 21. Test Circuit for Typical Regions of Stability (Figures 22 through 25) (Fixed Output Options)

TYPICAL CHARACTERISTICS

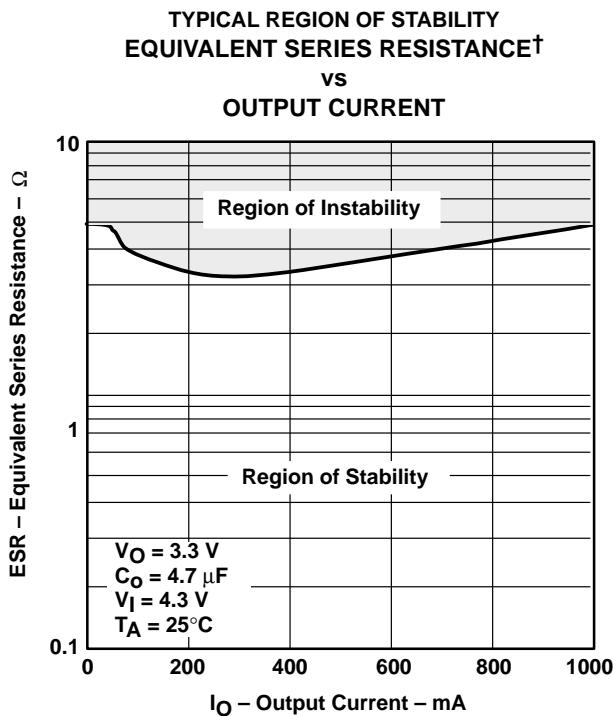


Figure 22

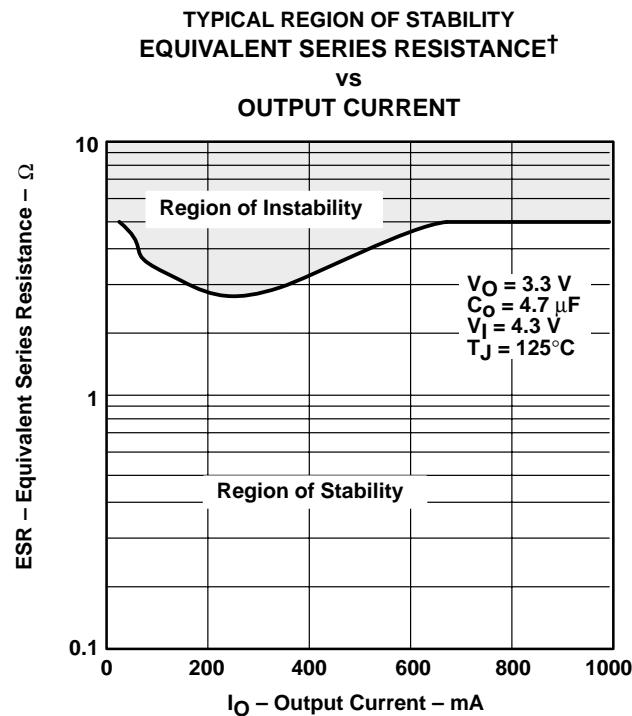


Figure 23

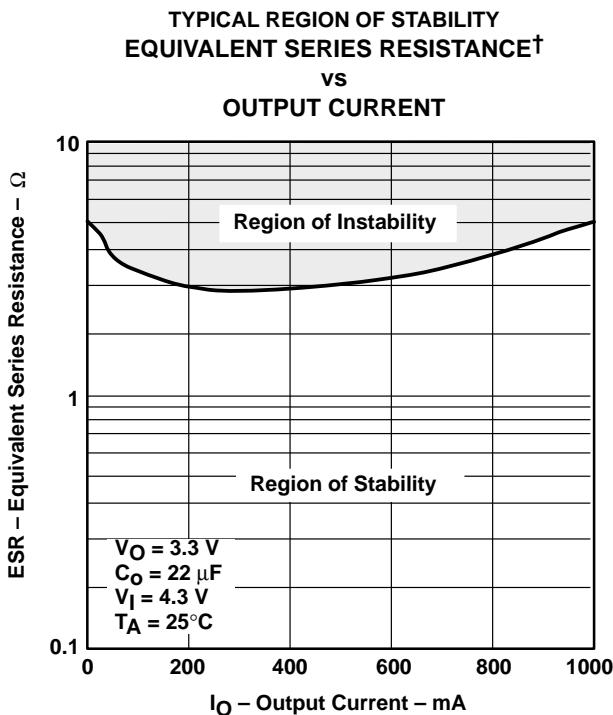


Figure 24

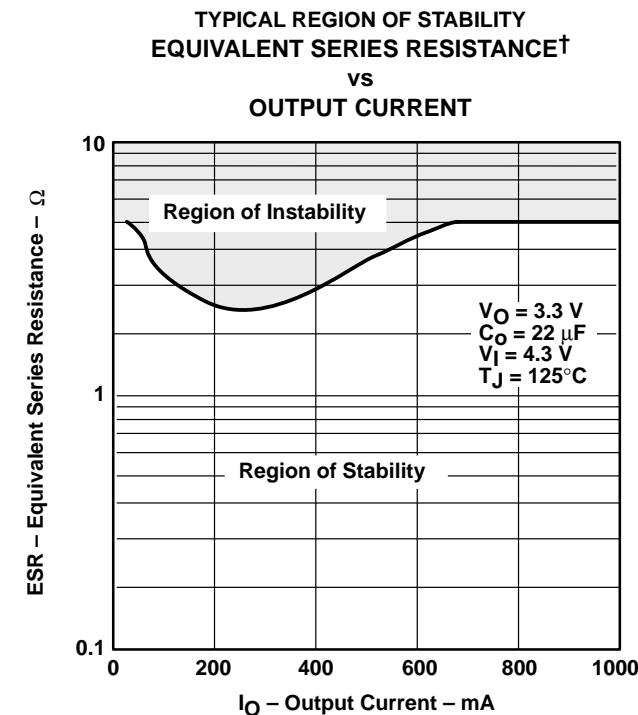


Figure 25

† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O .

**TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76727-EP
TPS76728-EP, TPS76730-EP, TPS76733-EP, TPS76750-EP, TPS76701-EP
FAST-TRANSIENT-RESPONSE 1-A LOW-DROPOUT VOLTAGE REGULATORS**

SGLS157 – MARCH 2003

APPLICATION INFORMATION

The TPS767xx family includes eight fixed-output voltage regulators (1.5 V, 1.8 V, 2.5 V, 2.7 V, 2.8 V, 3.0 V, 3.3 V, and 5.0 V), and an adjustable regulator, the TPS76701 (adjustable from 1.5 V to 5.5 V).

device operation

The TPS767xx features very low quiescent current, which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). The TPS767xx uses a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS767xx quiescent current remains low even when the regulator drops out, eliminating both problems.

The TPS767xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to 2 μ A. If the shutdown feature is not used, EN should be tied to ground.

minimum load requirements

The TPS767xx family is stable even at zero load; no minimum load is required for operation.

FB—pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option. The output voltage is sensed through a resistor divider network to close the loop as shown in Figure 27. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential.

external capacitor requirements

An input capacitor is not usually required; however, a ceramic bypass capacitor (0.047 μ F or larger) improves load transient response and noise rejection if the TPS767xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of millamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS767xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 μ F and the ESR (equivalent series resistance) must be between 50 m Ω and 1.5 Ω . Capacitor values 10 μ F or larger are acceptable, provided the ESR is less than 1.5 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 10 μ F surface-mount ceramic capacitors, including devices from Sprague and Kemet, meet the ESR requirements stated above.

APPLICATION INFORMATION

external capacitor requirements (continued)

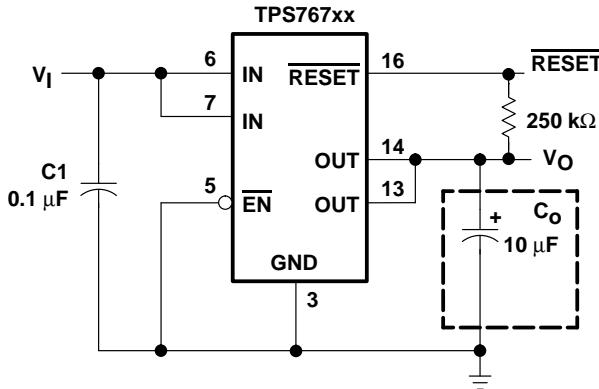


Figure 26. Typical Application Circuit (Fixed Versions)

programming the TPS76701 adjustable LDO regulator

The output voltage of the TPS76701 adjustable regulator is programmed using an external resistor divider as shown in Figure 27. The output voltage is calculated using:

$$V_O = V_{\text{ref}} \times \left(1 + \frac{R1}{R2} \right) \quad (1)$$

Where:

$V_{\text{ref}} = 1.1834 \text{ V typ}$ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 50-μA divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose $R2 = 30.1 \text{ k}\Omega$ to set the divider current at 50 μA and then calculate R1 using:

$$R1 = \left(\frac{V_O}{V_{\text{ref}}} - 1 \right) \times R2 \quad (2)$$

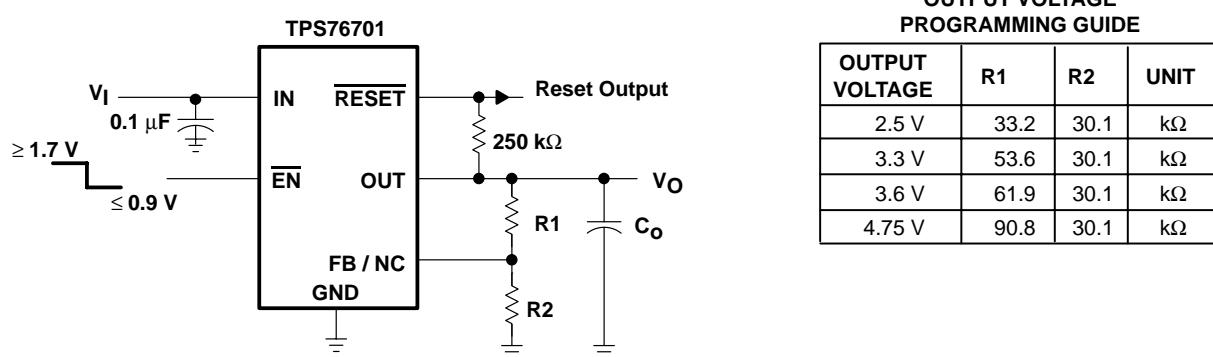


Figure 27. TPS76701 Adjustable LDO Regulator Programming

APPLICATION INFORMATION

reset indicator

The TPS767xx features a RESET output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the RESET output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. RESET can be used to drive power-on reset circuitry or as a low-battery indicator. RESET does not assert itself when the regulated output voltage falls outside the specified 2% tolerance, but instead reports an output voltage low relative to its nominal regulated value (refer to timing diagram for start-up sequence).

regulator protection

The TPS767xx PMOS-pass transistor has a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS767xx also features internal current limiting and thermal protection. During normal operation, the TPS767xx limits output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(\max)}$, and the actual dissipation, P_D , which must be less than or equal to $P_{D(\max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(\max)} = \frac{T_{J\max} - T_A}{R_{\theta JA}}$$

Where:

$T_{J\max}$ is the maximum allowable junction temperature.

$R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 172°C/W for the 8-terminal SOIC and 32.6°C/W for the 20-terminal PWP with no airflow.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times I_O$$

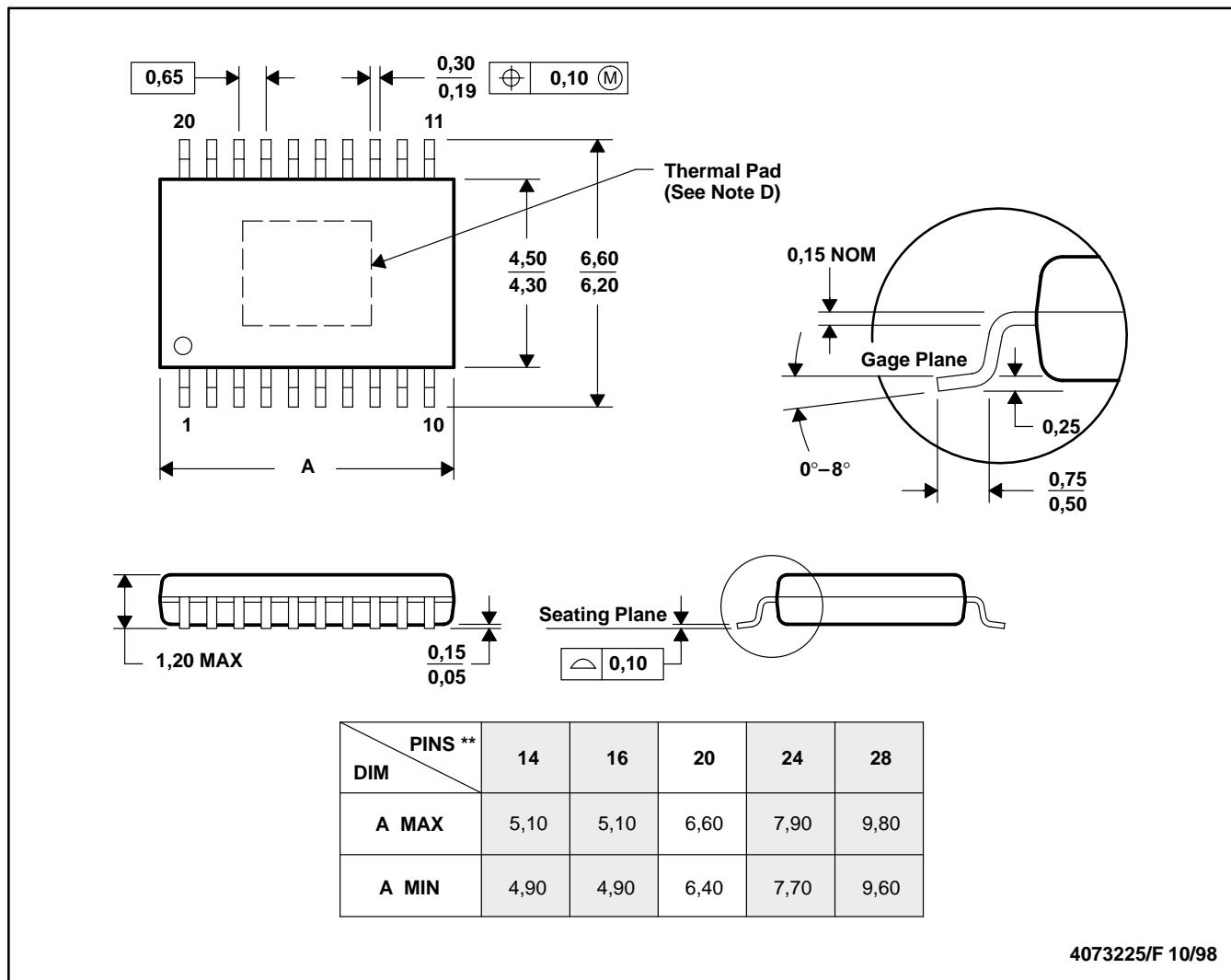
Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

MECHANICAL DATA

PWP (R-PDSO-G)**

20 PINS SHOWN

PowerPAD™ PLASTIC SMALL-OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusions.
- D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments Incorporated.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS76701QPWPREP	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76701QE	Samples
TPS76715QPWPREP	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76715QE	Samples
TPS76718QPWPREP	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76718QE	Samples
TPS76725QPWPREP	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76725QE	Samples
TPS76733QPWPREP	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76733QE	Samples
TPS76750QPWPREP	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76750QE	Samples
V62/03630-01XE	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76701QE	Samples
V62/03630-02XE	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76715QE	Samples
V62/03630-03XE	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76718QE	Samples
V62/03630-04XE	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76725QE	Samples
V62/03630-08XE	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76733QE	Samples
V62/03630-09XE	ACTIVE	HTSSOP	PWP	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	76750QE	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TPS76701-EP, TPS76715-EP, TPS76718-EP, TPS76725-EP, TPS76733-EP, TPS76750-EP :

• Catalog: [TPS76701](#), [TPS76715](#), [TPS76718](#), [TPS76725](#), [TPS76733](#), [TPS76750](#)

• Automotive: [TPS76701-Q1](#), [TPS76715-Q1](#), [TPS76718-Q1](#), [TPS76725-Q1](#), [TPS76733-Q1](#), [TPS76750-Q1](#)

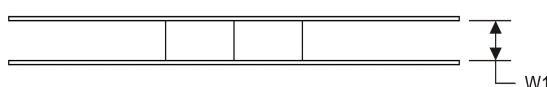
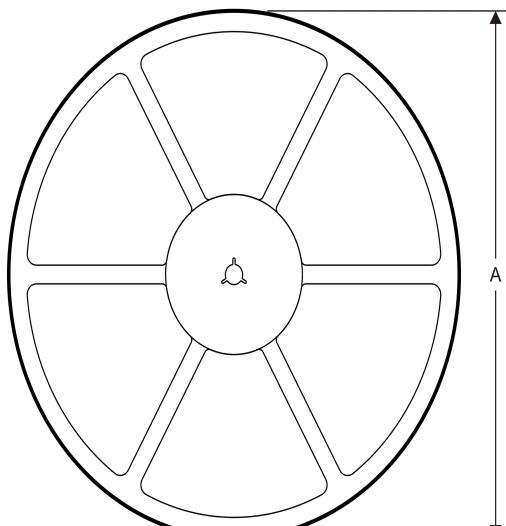
NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

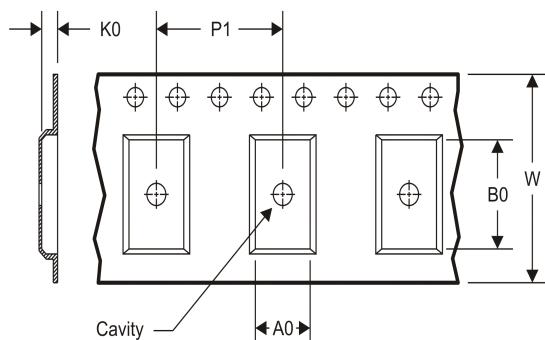
• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS

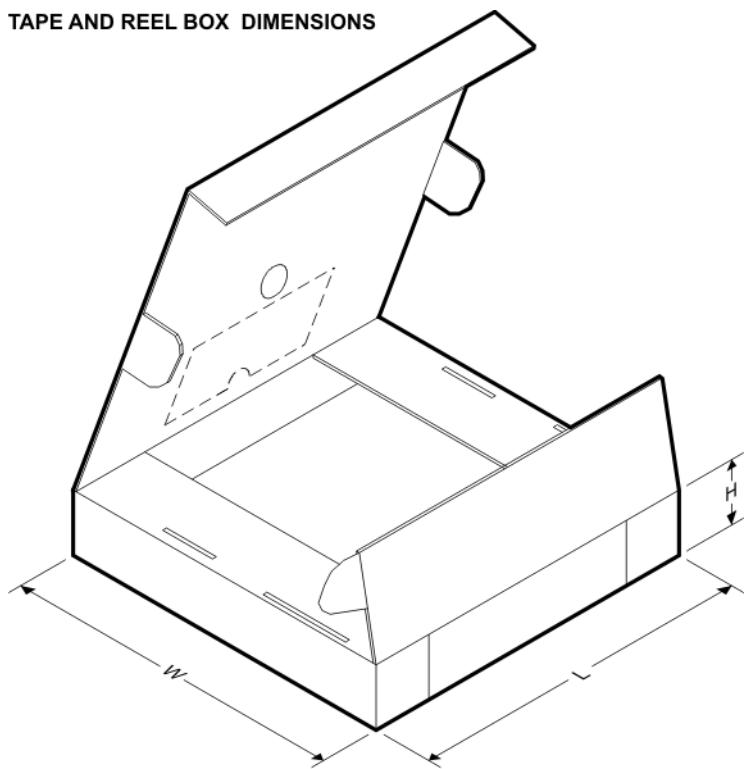


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76701QPWPREP	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS76715QPWPREP	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS76718QPWPREP	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS76725QPWPREP	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS76733QPWPREP	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TPS76750QPWPREP	HTSSOP	PWP	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


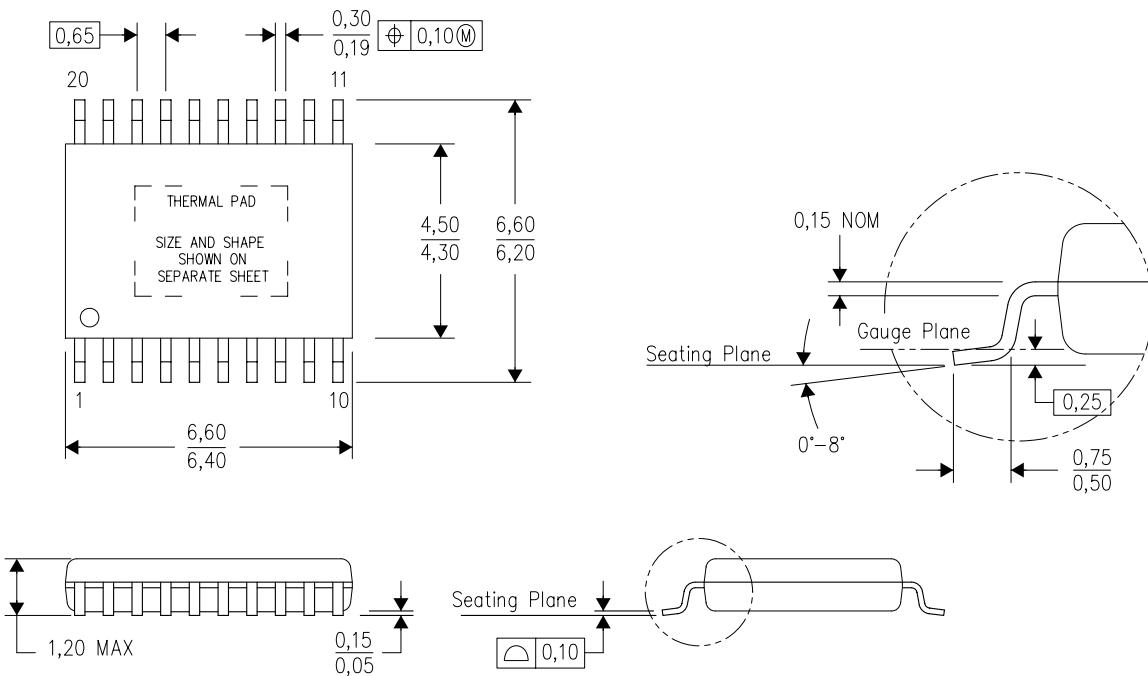
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76701QPWPREP	HTSSOP	PWP	20	2000	367.0	367.0	38.0
TPS76715QPWPREP	HTSSOP	PWP	20	2000	367.0	367.0	38.0
TPS76718QPWPREP	HTSSOP	PWP	20	2000	367.0	367.0	38.0
TPS76725QPWPREP	HTSSOP	PWP	20	2000	367.0	367.0	38.0
TPS76733QPWPREP	HTSSOP	PWP	20	2000	367.0	367.0	38.0
TPS76750QPWPREP	HTSSOP	PWP	20	2000	367.0	367.0	38.0

MECHANICAL DATA

PWP (R-PDSO-G20)

PowerPAD™ PLASTIC SMALL OUTLINE



4073225-4 / 05 / 11

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F. Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

PWP (R-PDSO-G20)

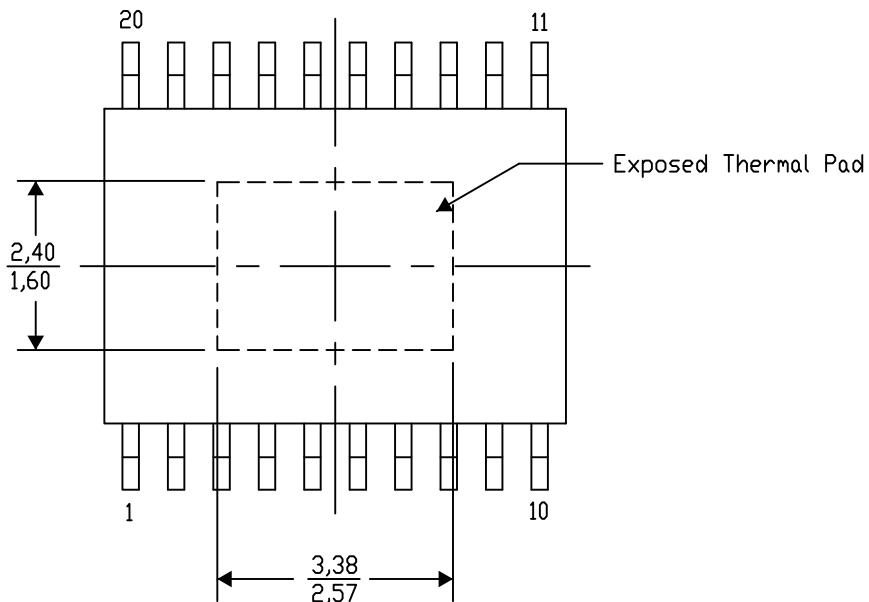
PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

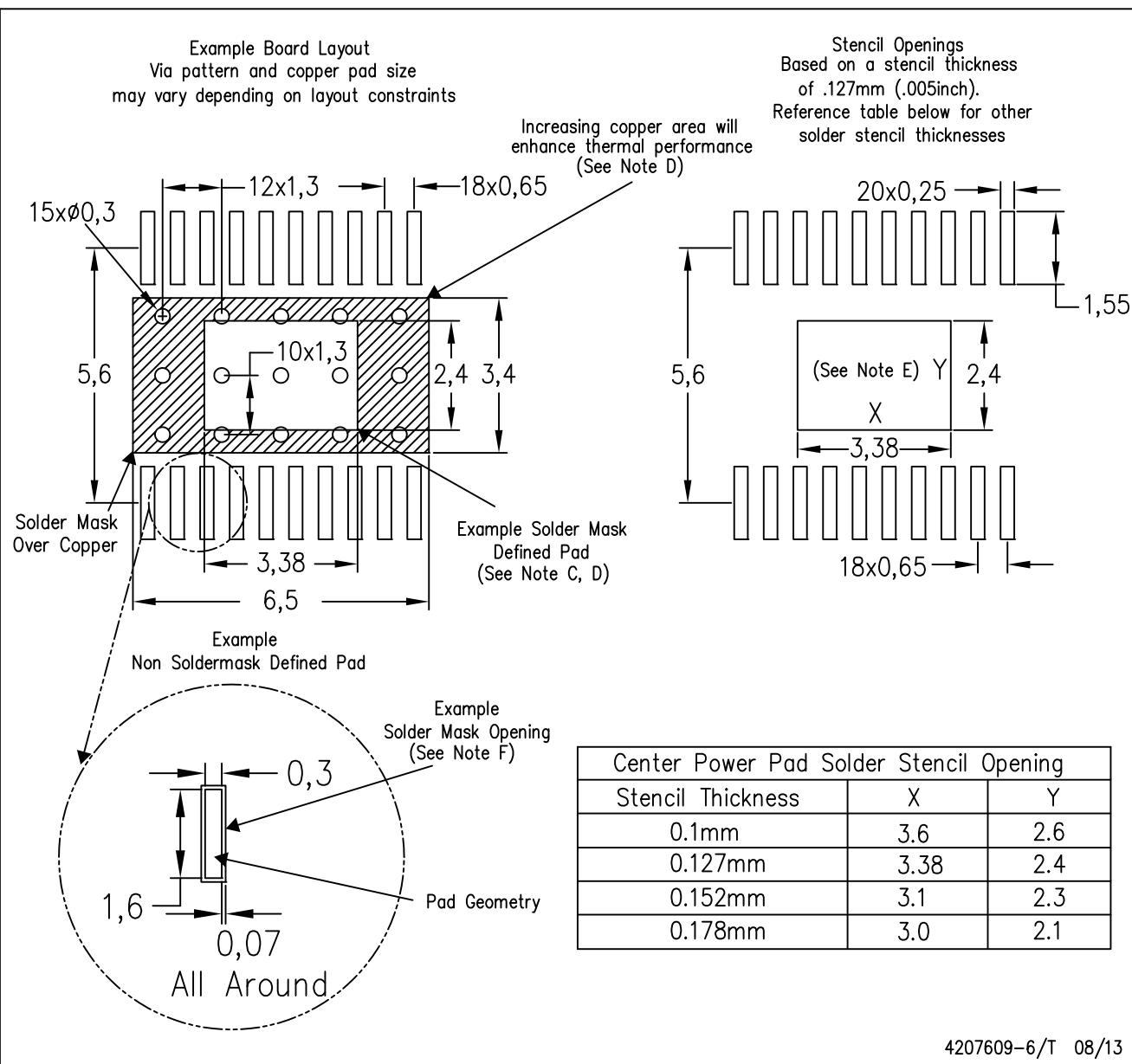
4206332-13/AH 11/13

NOTE: A. All linear dimensions are in millimeters

PowerPAD is a trademark of Texas Instruments

PWP (R-PDSO-G20)

PowerPAD™ PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

THERMAL PAD MECHANICAL DATA

PWP (R-PDSO-G20)

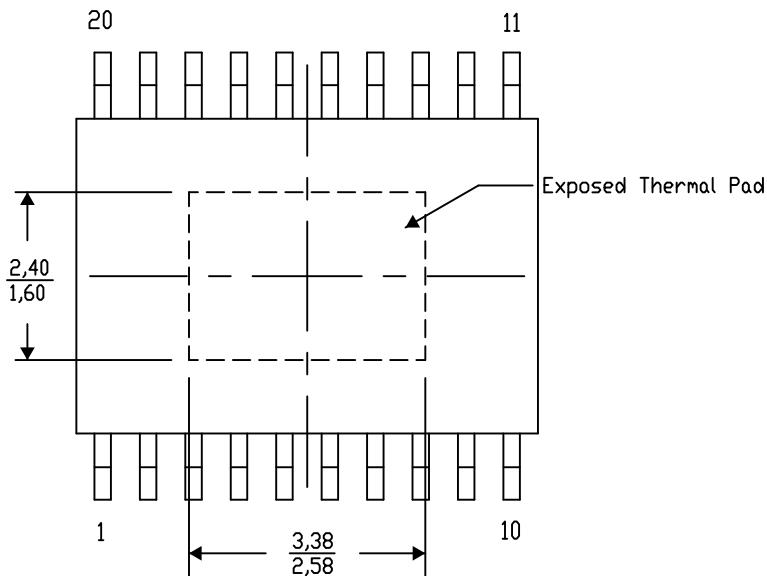
PowerPAD™ SMALL PLASTIC OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Top View

Exposed Thermal Pad Dimensions

4206332-21/AH 11/13

NOTE: A. All linear dimensions are in millimeters

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TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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Данный компонент на территории Российской Федерации**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибуторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ Р В 0015-002 и ЭС РД 009

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